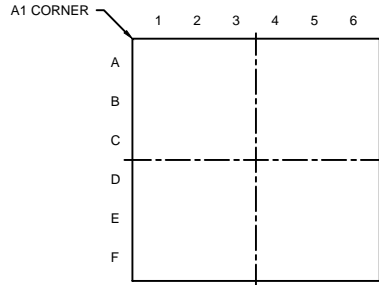
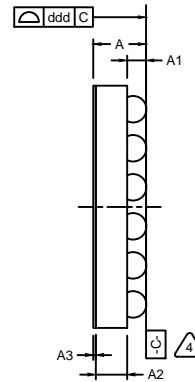


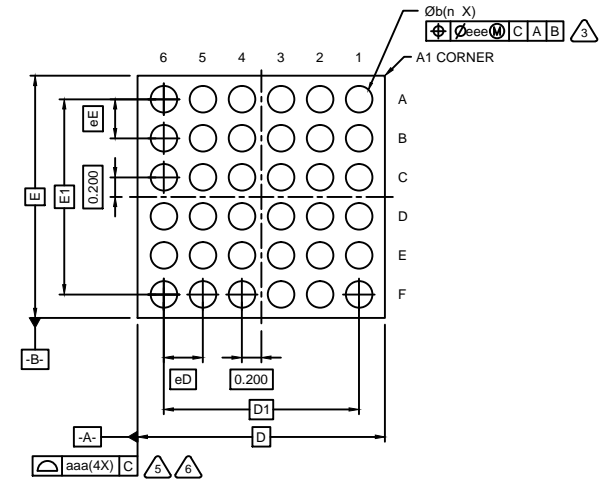
TOP VIEW



SIDE VIEW



BOTTOM VIEW



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DG4.18

	SYMBOL	COMMON DIMENSIONS		
		MIN.	NOM.	MAX.
Total Thickness	A	0.502	0.541	0.580
Stand Off	A1	0.164	0.194	0.224
Wafer Thickness	A2	0.322 ± 0.025		
Backside Coating Thickness	A3	0.025		
Body Size	D	2.536 BSC		
	E	2.482 BSC		
Ball Diameter (Size)		0.250		
Ball/Bump Width	b	0.200	0.250	0.300
Ball/Bump Pitch	eD	0.400		
	eE	0.400		
Ball/Bump Count	n	36		
Edge Ball Center to Center	D1	2.000 BSC		
	E1	2.000 BSC		
Package Edge Tolerance	aaa	0.030		
Coplanarity (whole wafer)	ddd	0.030		
Ball/Bump Offset (Package)	eee	0.015		

Title: Package Outline Drawing

Pkg Type: WLCSP

Document No:

Product Family: LFMXO4

Pin Count: 36

POD-250071

Product Name: LFMXO4-015-UUG36

Pkg Size: 2.536x2.482 mm

Rev: A

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